



Final Product Change Notification

202302013F01 : For LPC176x in LQFP100, TFME Will be Added as a 2nd Source Assembly Site

Note: This notice is NXP Company Proprietary.

Issue Date: Feb 27, 2023 **Effective date:** May 28, 2023

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Management summary

For LPC176x in LQFP100, TFME will be added as a 2nd source assembly site.

Change Category

- | | | | | |
|--|--|---|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input checked="" type="checkbox"/> Product Marking | <input type="checkbox"/> Test Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input checked="" type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware <input type="checkbox"/> Other | | | | |

PCN Overview

Description

For products LPC176xFBD100, TFME will be added as a 2nd source assembly site.

The assembly materials (mold compound, die attach and bond wire) also change. See the attached self qualification report for details.

Reason

Supply continuity.

Identification of Affected Products

Top Side Marking

The assembly site code is located in the last line of the top side marking. See the attached self qualification report for marking details.

Product Availability

Sample Information

Samples are available upon request

Samples of superset part number LPC1768FBD100 are available.

Production

Planned first shipment May 28, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Once PCN is effective, customer may receive product from either assembly site.

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Mar 29, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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